



Remarks

The present application has been reviewed in light of the Office Action dated February 23, 2006. By the foregoing amendment, claim 1 was amended and claims 2-3 were cancelled without prejudice. Applicant submits that no new matter was added by the amendment, as all of the amended matter was described or illustrated in the drawings, written specification, and claims of the present application as originally filed.

The Examiner has rejected claims 1-4 and 7-10 under 35 U.S.C. 102(b) as being anticipated by Inaba et al. (U.S. Pat. No. 5,408,052). The Examiner has also rejected claim 12 under 35 U.S.C. 103(a) as being unpatentable over Inaba et al.

As amended, independent claim 1 and all of the claims dependent thereon require, among other limitations, (i) that a first conductive layer be formed on an outer surface of the base film including an area covering the first and second connection holes of the base film, (ii) that a second conductive layer be formed on an inner surface of the base film including an area covering the first connection hole of the base film, in which said second conductive layer formation area excludes the main portion of the base film, (iii) that a third conductive layer be formed on an inner surface of the base film including an area covering the second connection hole of the base film, in which said third conductive layer formation area excludes the end portion and the interim portion of the base film, (iv) that a first cover layer be formed of a flexible insulation

material and covering the first conductive layer, and (v) that a second cover layer be formed of a flexible insulation material and covering the third conductive layer, in which said second cover layer formation area excludes the end portion and the interim portion of the base film such that the flexible printed circuit board is subject to repeated bending primarily at the interim portion thereof without developing cracks in the bending portion.

Inaba et al. (U.S. Pat. No. 5,408,052) discloses a flexible multi-layer circuit wiring board having a flexible base member 1, circuit wiring conductors 4, and circuit conductors 2 partially protruding beyond the ends of the flexible base member 1 to constitute finger lead-like terminals 3. (Col. 2, lines 18-27 and lines 38-47). A surface protection layer 8 comprised of an adhesive layer 6 and an insulating layer 7 is formed on each opposite surface of the circuit conductors 2 and the circuit wiring conductors 4, "inclusive of those of the bent portion A". (Col. 2, lines 48-53).

The Examiner indicates that one of the surface protection layers 8 (i.e., lower layer 8) of Inaba et al. is analogous to the first cover layer of the present invention as claimed, which covers the first conductive layer, and the other one of the surface protection layers 8 (i.e., upper layer 8) to the second cover layer of the present invention as claimed, which covers the third conductive layer. See the Office Action, at Page 3, lines 3-5. However, as stated above, this upper protection layer 8 covers on the entire upper surface of the Inaba et al. device, "inclusive of those of the bent portion A". There

is absolutely no suggestion found in the Inaba et al. disclosure that teaches the formation area of the upper protection layer 8 can exclude any interim portion or end portion of the device as required by the invention as claimed. Therefore, Inaba et al. fails to disclose or teach, among others, the above-identified limitation (v) of the claimed invention requiring exclusion of the covering area on the end portion and the interim portion of the base film.

Moreover, Inaba et al. further fails to disclose or teach the above-identified limitation (iii) of the claimed invention. Contrary to the claimed invention requiring that the third conductive layer be formed on an inner surface of the base film including an area covering the second connection hole of the base film, however, excluding the end portion and the interim portion of the base film, each of the circuit conductor layers 2 of Inaba et al. is formed on the respective end portion of the device and on an outer surface thereof. See FIG. 1 and associated descriptions of Inaba et al.

Accordingly, because Inaba et al. fails to disclose or teach, among others, at least the above-identified limitations (iii) and (v) of the claimed invention, claims 1, 4, 7-10, and 12 as amended are patentably distinct over Inaba et al.

The Examiner has rejected claims 5 and 6 under 35 U.S.C. 103(a) as being unpatentable over Inaba et al., above discussed, in view of Yoon et al. (U.S. Pat. No. 6,041,495). The Examiner has further rejected claim 11 under 35 U.S.C. 103(a) as

being unpatentable over Inaba et al., above discussed, in view of Kobayashi et al. (U.S. Pat. No. 5,471,438).

Claims 5, 6, and 11 are all dependent on independent claim 1, thus patentable at least for the reasons that claim 1 is patentable as discussed above. Applicant further submits that, similar to Inaba et al. discussed above, Yoon et al. (U.S. Pat. No. 6,041,495) and Kobayashi et al. (U.S. Pat. No. 5,471,438) also fail to disclose or teach, among others, at least the above-identified limitations (iii) and (v) of the claimed invention.

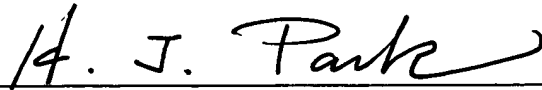
Applicant further respectfully submits that it would not have been obvious to modify the cited references, either alone or when combined, to arrive at the present invention as claimed. It is well settled that the mere fact that references can be combined or modified does not render the resultant combination obvious unless the prior art also suggests the desirability of the modification or combination. *In re Mills*, 916 F.2d 680, 16 U.S.P.Q.2d 1430 (Fed. Cir. 1990). In the present case, Applicant respectfully submits that there is absolutely no motivation provided in either of the references to make the modifications necessary to arrive at the claimed invention.

For the foregoing reasons, Applicant respectfully submits that all pending claims, namely Claims 1 and 4-12, are patentable over the references of record, and earnestly solicits allowance of the same.

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Response to Official Action

Respectfully submitted,

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A handwritten signature in black ink, appearing to read "W. J. Park", written over a horizontal line.

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